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Rohm DC/DC Micro Converter TDK-EPC Embedded Die Process Reverse Costing Analysis

Description:

Rohm and TDK-EPC have joined forces to provide an alternative solution for embedded die technology. This SiP module is a second-source supply of the Texas Instruments MicroSiP™DC-DC Converter. Although fully compatible, the process and cost structure is very different from the previously analyzed TI module with a packaging performed by AT&S.

Embedded die packaging is an emerging solution to increase the integration in mobile products. This technology is supported by a game-changing, low-cost, panel-based PCB infrastructure that has the potential to create an alternative supply chain for today's well established packaging standards.

This report provides complete teardown of the Embedded die package with:

- Detailed photos
- Material analysis
- Schematic assembly description
- Manufacturing Process Flow
- Cost analysis, step by step
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- Selling price estimation

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